

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
BIKIRAN GOSWAMI	06/15/2015
BAOXING CHEN	06/15/2015
RECEIVING PARTY DATA	
Name:	ANALOG DEVICES, INC.
Street Address:	ONE TECHNOLOGY WAY
City:	NORWOOD
State/Country:	MASSACHUSETTS
Postal Code:	02062-9106
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14735104
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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ATTORNEY DOCKET NUMBER:	13641/529302
NAME OF SUBMITTER:	YULIYA ARTSISHEUSKAYA
SIGNATURE:	/Yuliya Artsisheuskaya/
DATE SIGNED:	07/01/2015
Total Attachments: 1	
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ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned hereby sell, assign, and transfer to **Analog Devices, Inc.**, a corporation of the state of Massachusetts, having a principal place of business at One Technology Way, Norwood, Massachusetts, 02062-9106 ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all inventions and discoveries that are disclosed in the United States Patent Application entitled:

CIRCUITS AND SYSTEMS FOR MULTIPLEXED ISOLATOR COMMUNICATION


the specification of which is attached hereto unless the following is entered:

filed on	as United States Application Number	and amended on (if applicable)
June 9, 2015	14/735,104	


and in and to said United States Patent Application and all provisional, divisional, continuing, substitute, renewal, reissue, and other patent applications that have been or shall be filed in the United States or any foreign country on any of said inventions and discoveries; and in and to all original and reissued patents that have been or shall be issued in the United States or any foreign country on said inventions and discoveries; and in and to all rights of priority resulting from the filing of said United States Patent Application;

agree that said Assignee may apply for and receive a patent or patents for said inventions and discoveries in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all provisional, divisional, continuing, substitute, renewal, reissue, and other patent applications on any and all said inventions and discoveries; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and representatives all facts known to the undersigned relating to said inventions and discoveries and the history thereof; and generally assist said Assignee, its successors, assigns, or representatives in securing and maintaining proper patent protection for said inventions and discoveries and for vesting title to said inventions and discoveries, and all applications for patents and all patents on said inventions and discoveries, in said Assignee, its successors, assigns, and legal representatives; and covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Inventor: **Bikiran Goswami**

Inventor Signature 	Date 6/15/2015
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Inventor: **Baoxing Chen**

Inventor Signature 	Date 6/15/2015
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